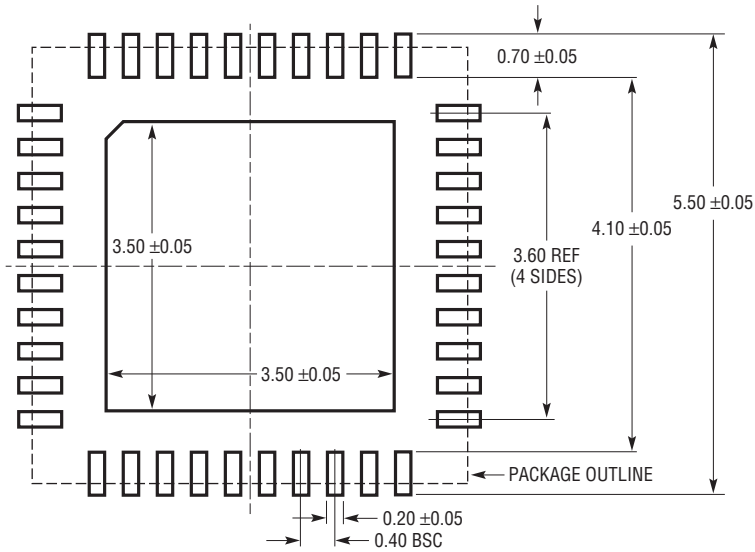
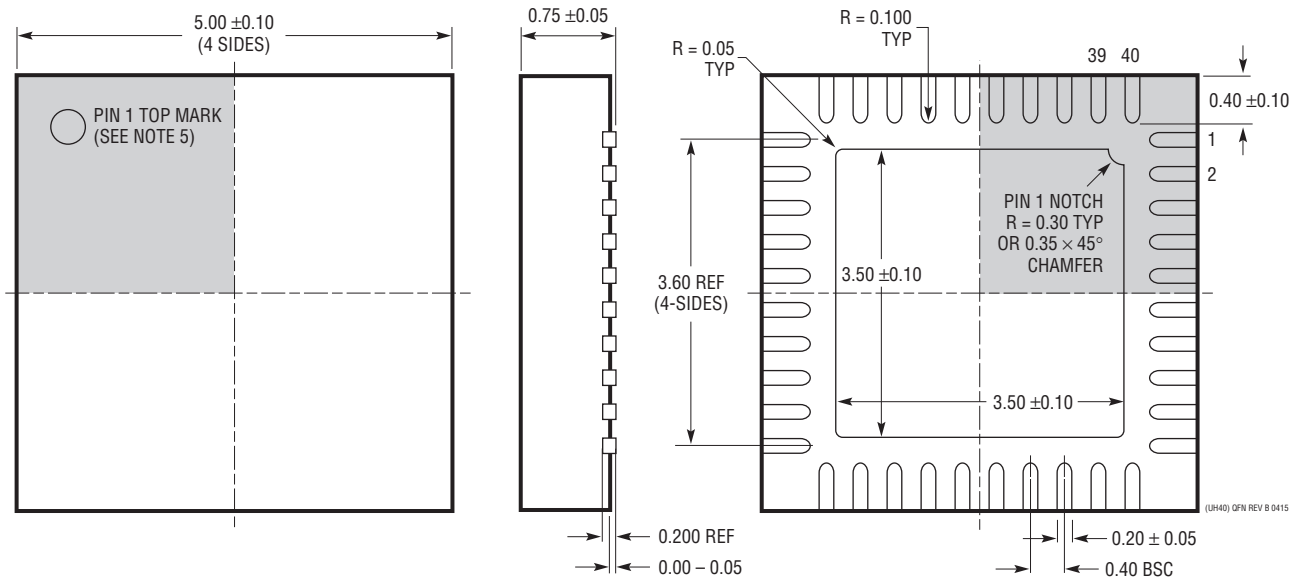


**UH Package**  
**40-Lead Plastic QFN (5mm × 5mm)**  
 (Reference LTC DWG # 05-08-1746 Rev B)



RECOMMENDED SOLDER PAD PITCH AND DIMENSIONS  
 APPLY SOLDER MASK TO AREAS THAT ARE NOT SOLDERED



NOTE:

1. DRAWING CONFIRMS TO JEDEC PACKAGE OUTLINE MO-220
2. ALL DIMENSIONS ARE IN MILLIMETERS
3. DIMENSIONS OF EXPOSED PAD ON BOTTOM OF PACKAGE DO NOT INCLUDE MOLD FLASH. MOLD FLASH SHALL NOT EXCEED 0.20mm ON ANY SIDE, IF PRESENT
4. EXPOSED PAD SHALL BE SOLDER PLATED
5. SHADED AREA IS ONLY A REFERENCE FOR PIN 1 LOCATION ON THE TOP AND BOTTOM OF PACKAGE
6. DRAWING NOT TO SCALE